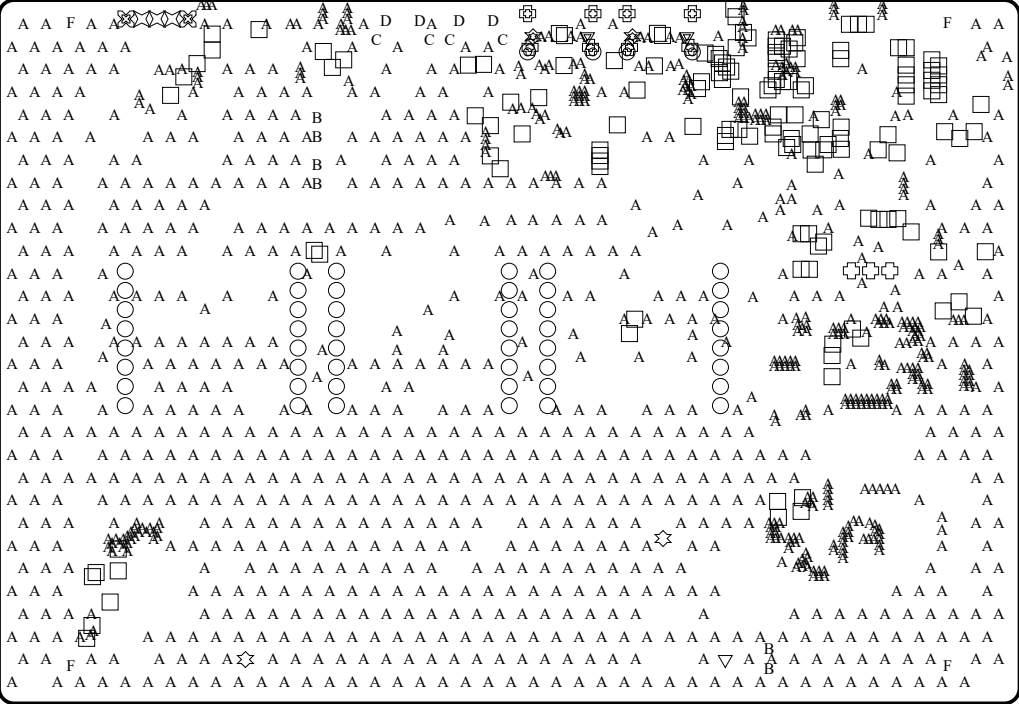


Project board: C213/C215
Revision: revC
PCBUBX number: UBXH60-0001010

Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
	Top Overlay			Legend	GTO
Surface Material	Top Solder	0.01mm(0mil)	Solder Resist	Solder Mask	GTS
Copper	L1	0.04mm(1mil)		Signal	GTL
Prepreg		0.11mm(4mil)	Composite dielectric	Dielectric	
Copper	L2	0.04mm(1mil)		Signal	G1
Core		1.20mm(47mil)	Composite dielectric	Dielectric	
Copper	L3	0.04mm(1mil)		Signal	G2
Prepreg		0.11mm(4mil)	Composite dielectric	Dielectric	
Copper	L4	0.04mm(1mil)		Signal	GBL
Surface Material	Bottom Solder	0.01mm(0mil)	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO
Total thickness: 1.59mm(62mil)					

Drill Drawing View (Scale 1:1)



Drill Table

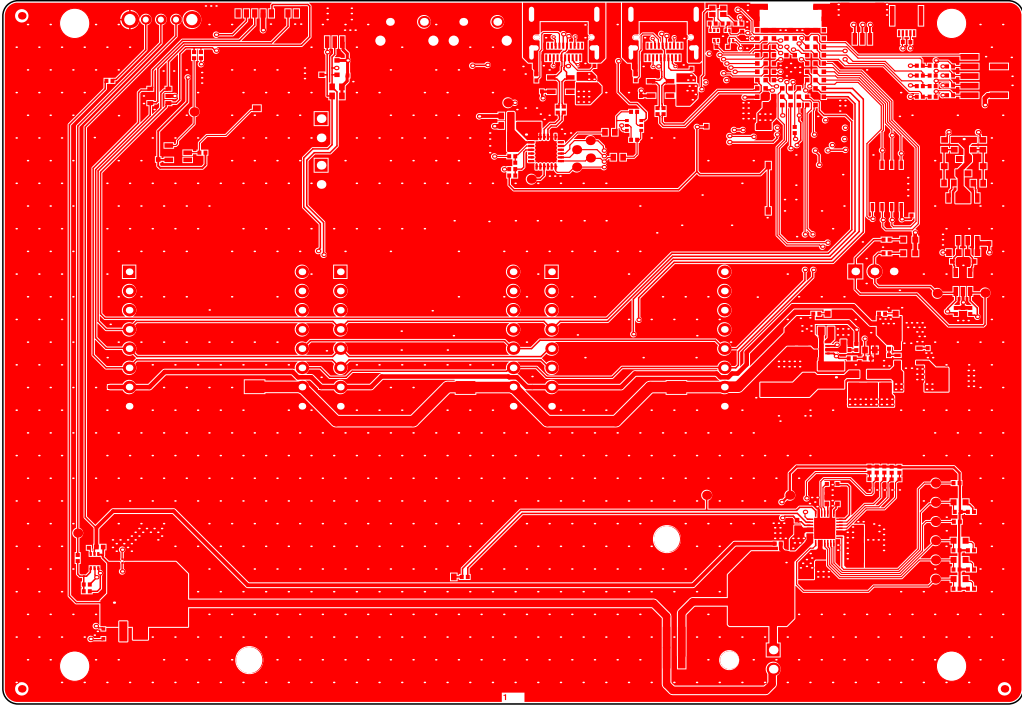
Symbol	Count	Hole Size	Plated
A	1125	0.20mm	Plated
□	148	0.30mm	Plated
✱	2	0.50mm	Non-Plated
▼	2	0.60mm	Non-Plated
◎	4	0.60mm	Plated
⊕	8	0.70mm	Plated
✕	3	0.80mm	Plated
○	48	0.89mm	Plated
⊕	3	1.02mm	Plated
D	4	1.04mm	Plated
B	6	1.15mm	Plated
C	4	1.35mm	Plated
✕	2	1.50mm	Plated
▼	1	2.39mm	Non-Plated
F	4	3.40mm	Non-Plated
✱	2	3.45mm	Non-Plated
	1366 Total		

Rev.	Description	Date	By
revA	Prototype Release	22/6/2022	tcha
revB	Second release	07/11/2022	tcha
revC	Changed uSD to push-push. Minor tweaks in power supply	06/04/2023	tcha
=ReleaseR	=ReleaseDesc4	=ReleaseDate4	=ReleaseB
=ReleaseR	=ReleaseDesc5	=ReleaseDate5	=ReleaseB

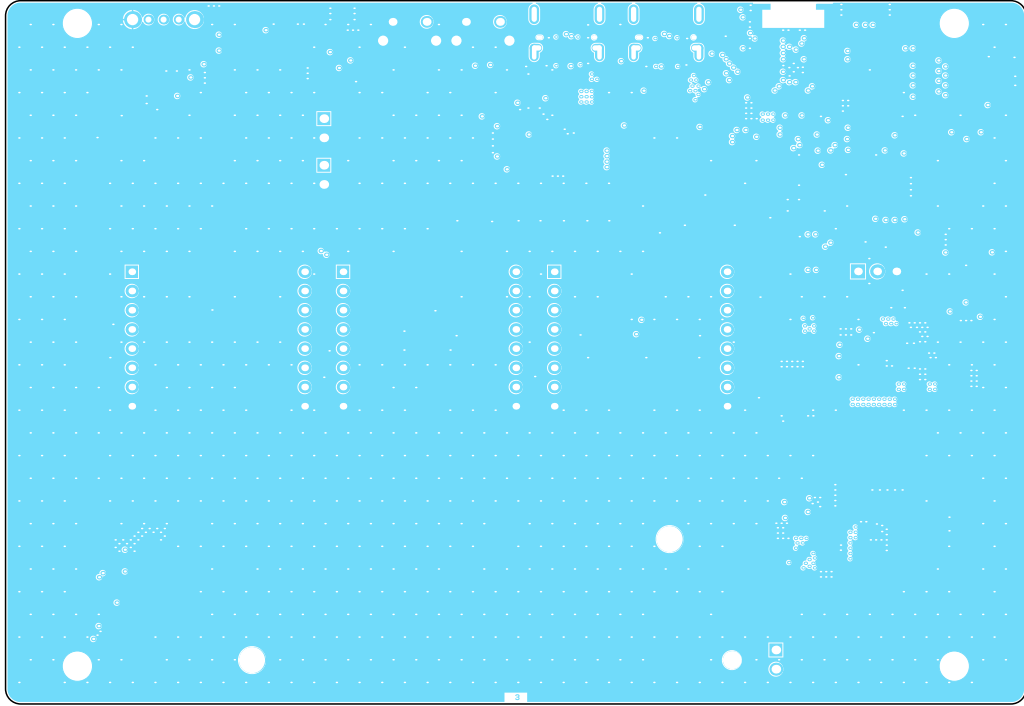


PCB NAME: ALPS-HPG		DATE: 06/04/2023
PROJECT: ALPS-HPG	ENGINEER: tcha	REVISION: revC
PCB NO: UBXH60-0001010	PRJ CODE: PGM-Alps	SHEET 1 of 5

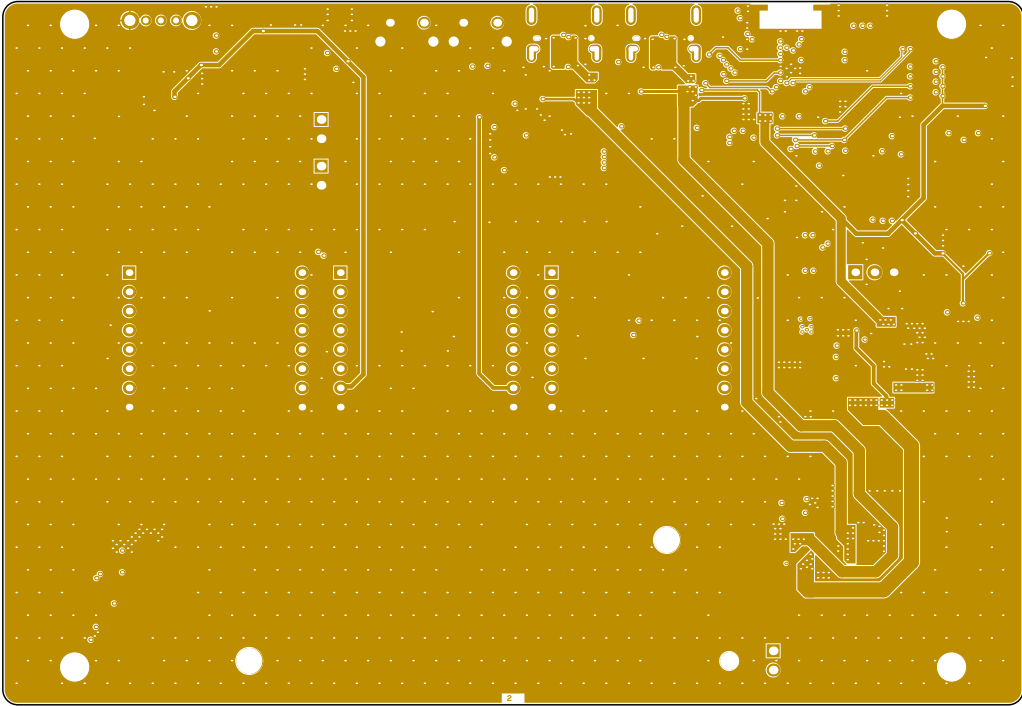
L1 (Scale 1:1)



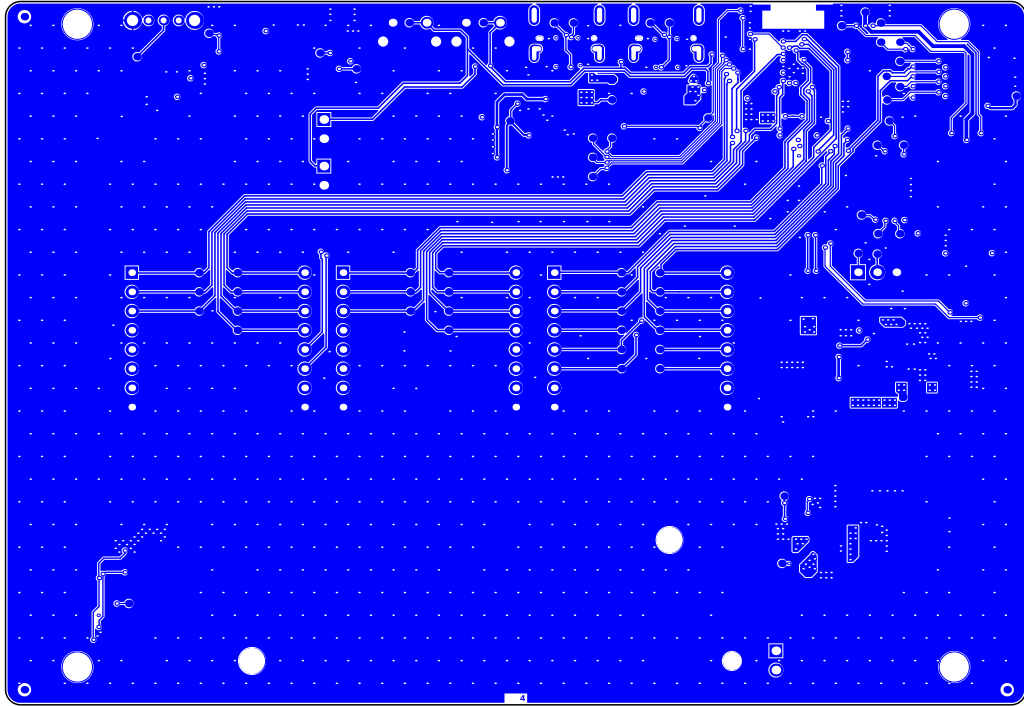
L3 (Scale 1:1)



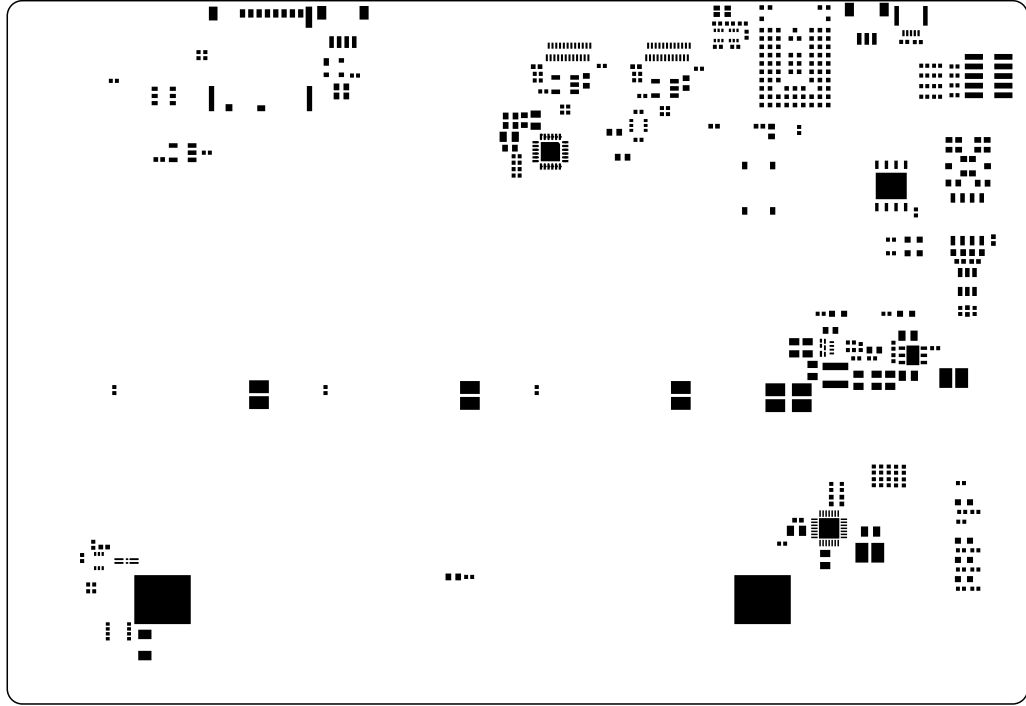
L2 (Scale 1:1)



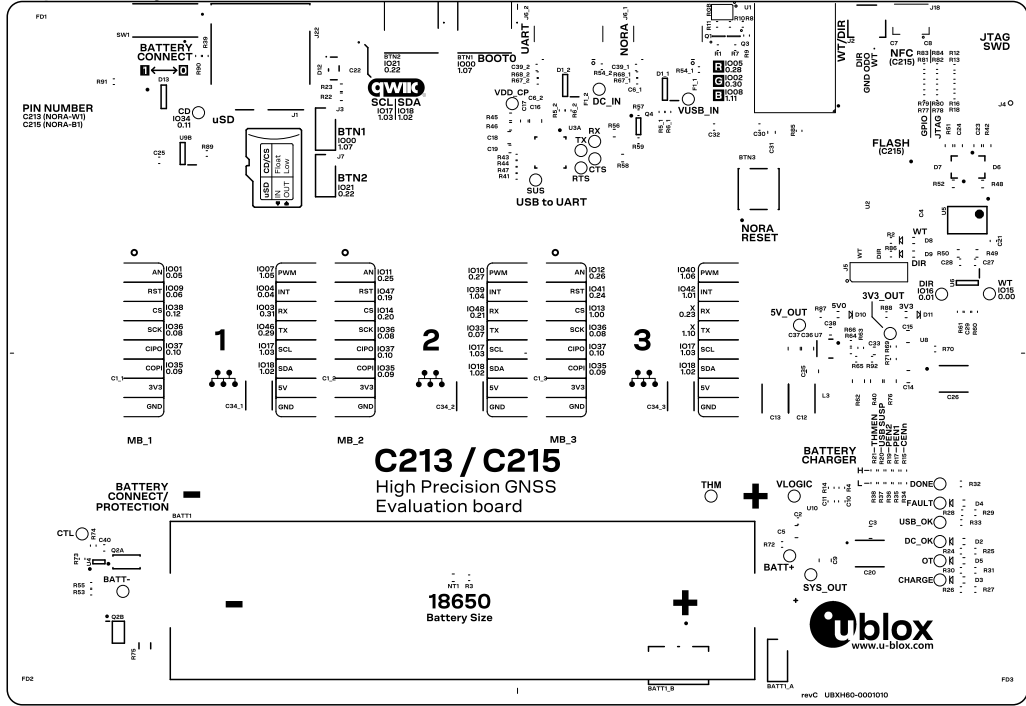
L4 (Scale 1:1)



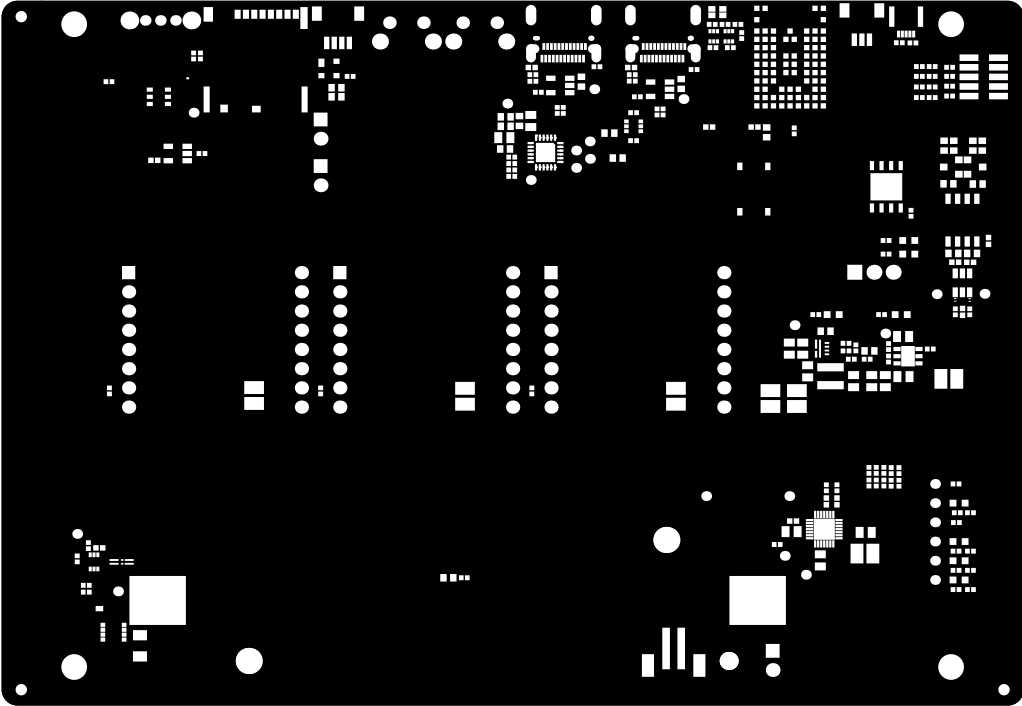
Top Paste (Scale 1:1)



Top Overlay (Scale 1:1)



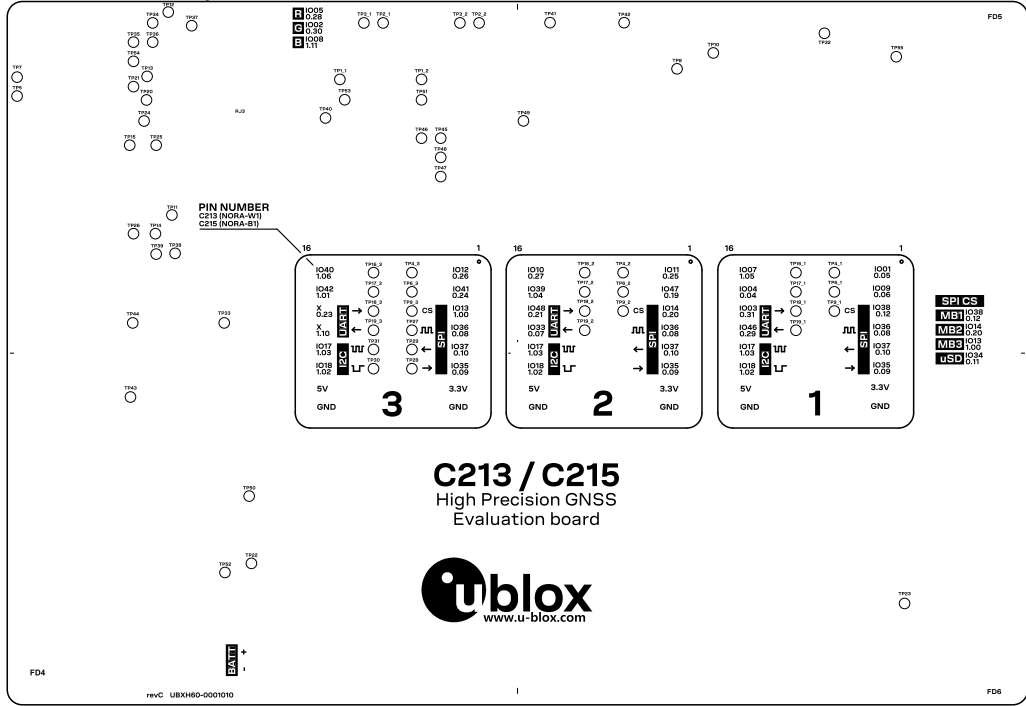
Top Solder (Scale 1:1)



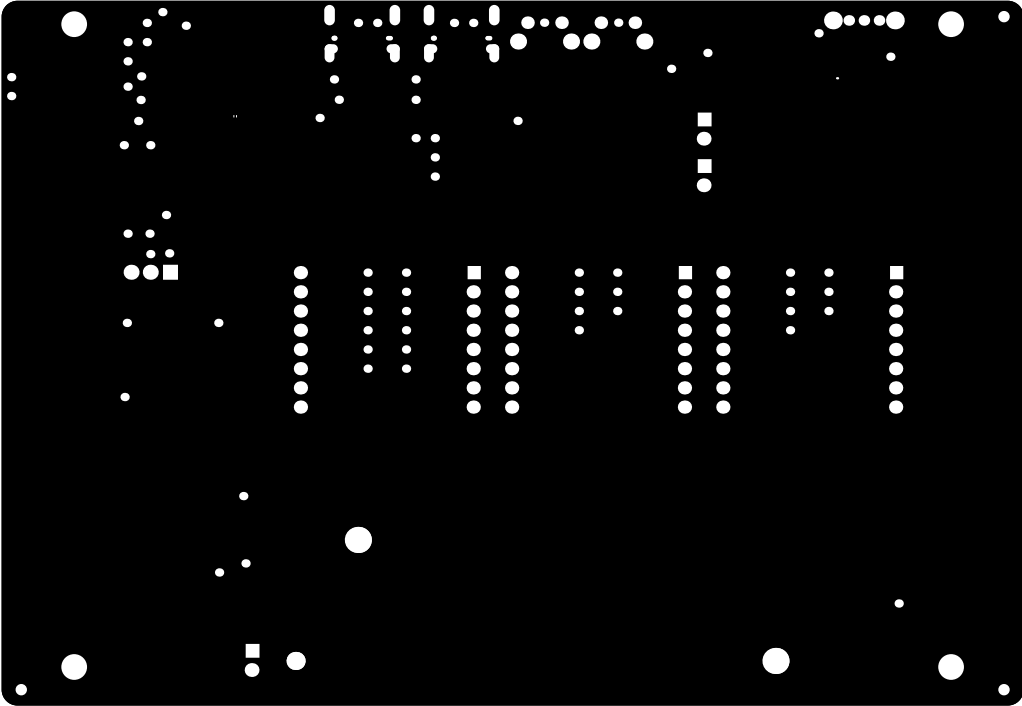
Bottom Paste (Scale 1:1)



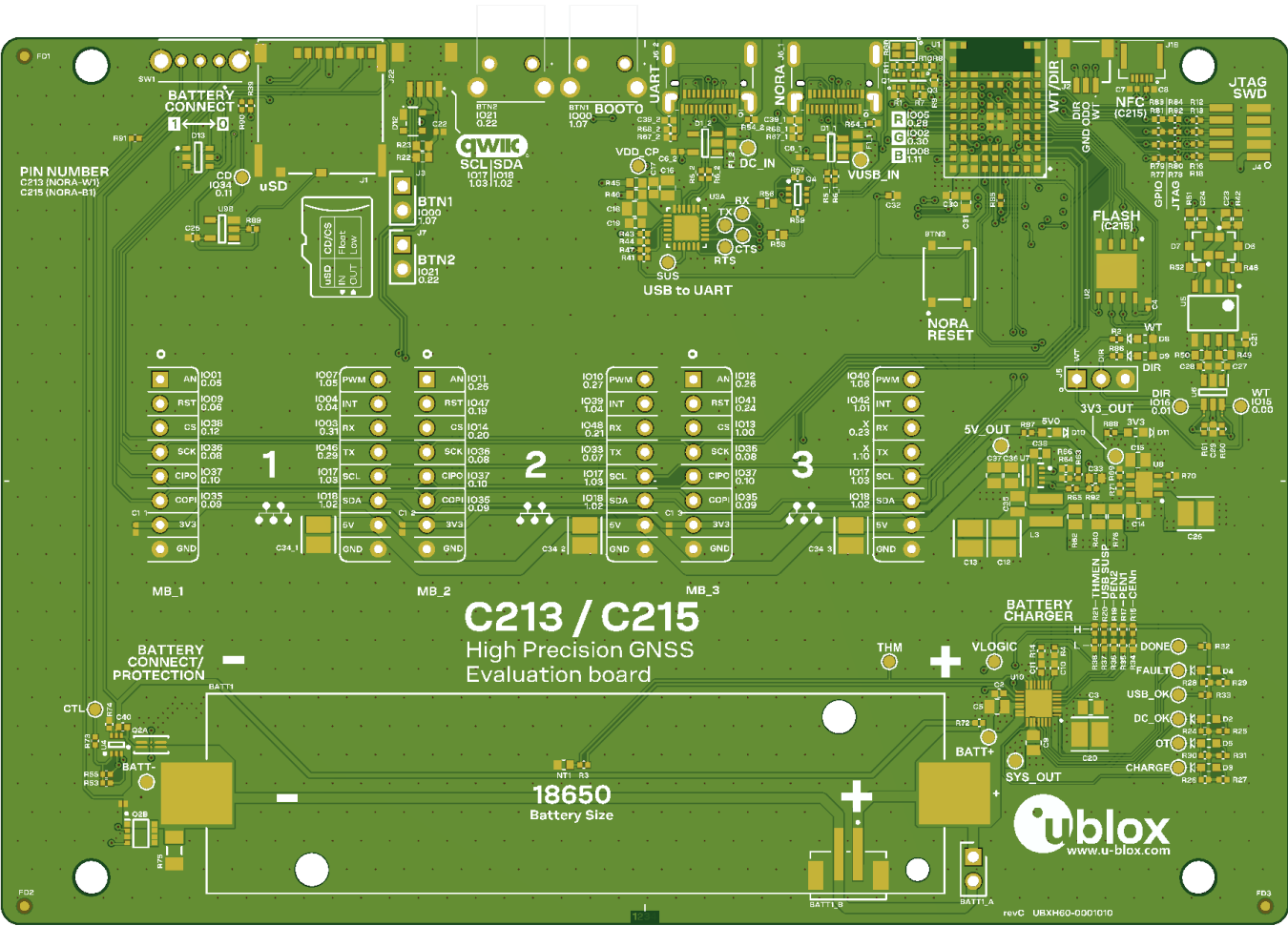
Bottom Overlay (Scale 1:1)



Bottom Solder (Scale 1:1)



Only PCB - Top



Only PCB - Bottom

